

DUAL DAMASCENE ANTI-FUSE WITH VIA BEFORE WIRE

ABSTRACT OF THE DISCLOSURE

An interconnect structure in which a patterned anti-fuse material is formed therein comprising: a substrate having
5 a first level of electrically conductive features; a patterned anti-fuse material formed on said substrate, wherein said patterned anti-fuse material includes an opening to at least one of said first level of electrically conductive features; a patterned interlevel dielectric material formed on said patterned anti-fuse material, wherein said patterned interlevel dielectric includes vias, at least one of said vias includes a via space; and a second level of electrically conductive features formed in said vias and via spaces.

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4 3 2 1 0 9 8 7 6 5 4 3 2 1 0